

A detailed cross-sectional view of a semiconductor device assembly, indicated by reference numeral 1. The assembly is built on a substrate 7, which has a bottom layer 8 and a top layer 17. A central component 14 is mounted on the substrate, secured by a cap 11a and a nut 11. A central vertical axis is shown with a dashed line 19. On either side of the center, there are symmetrical structures. Each side includes a base 5, a central core 12, and a top layer 17. The top layer 17 is connected to a horizontal bus or line 16. The entire assembly is enclosed within a housing or frame 18. Various other components and interfaces are labeled with numbers 1, 3, 10, 11, 12, 13, 14, 15, and 18.

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FIG. 3

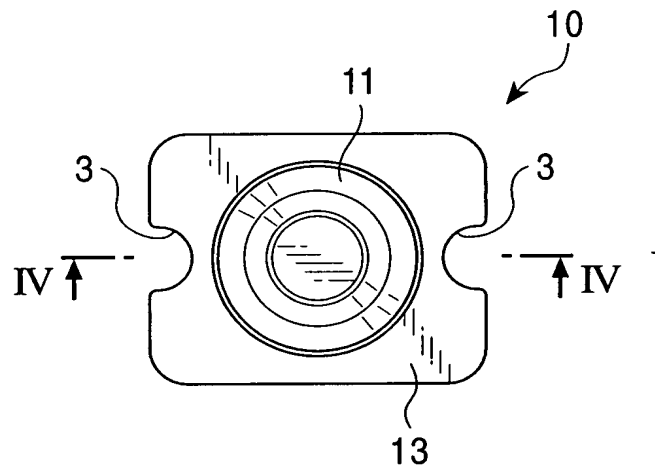
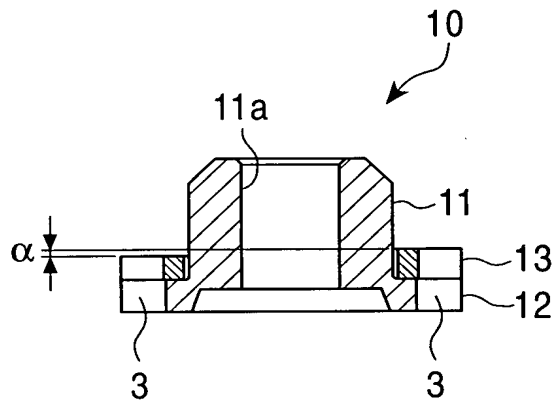


FIG. 4



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FIG. 5

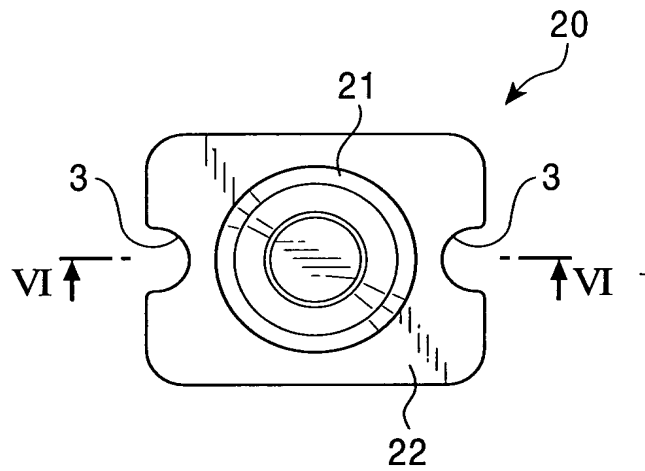
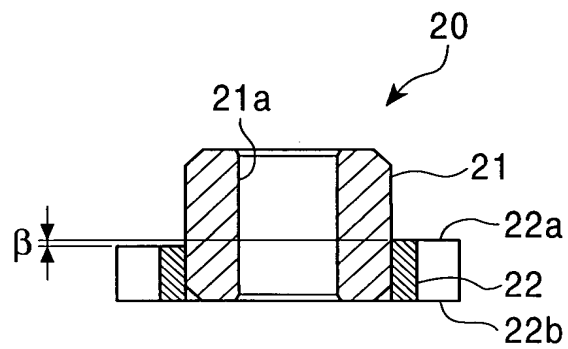


FIG. 6



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FIG. 7

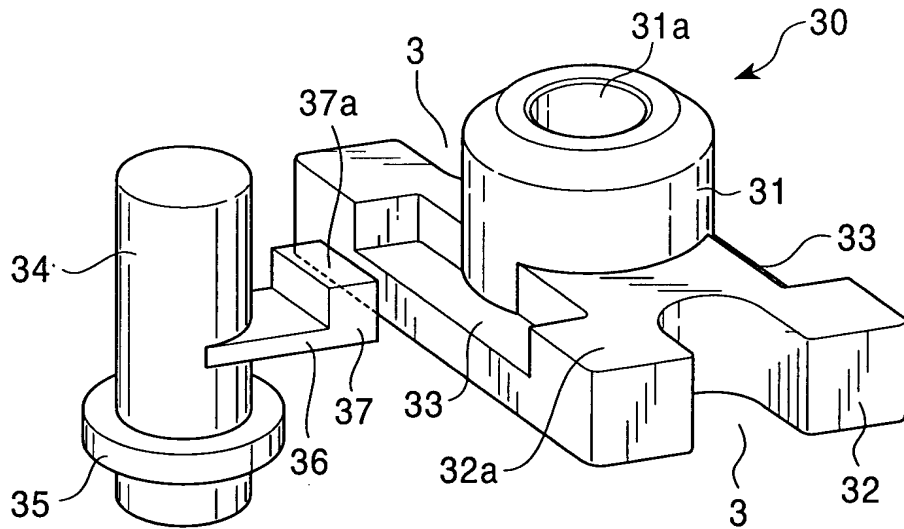
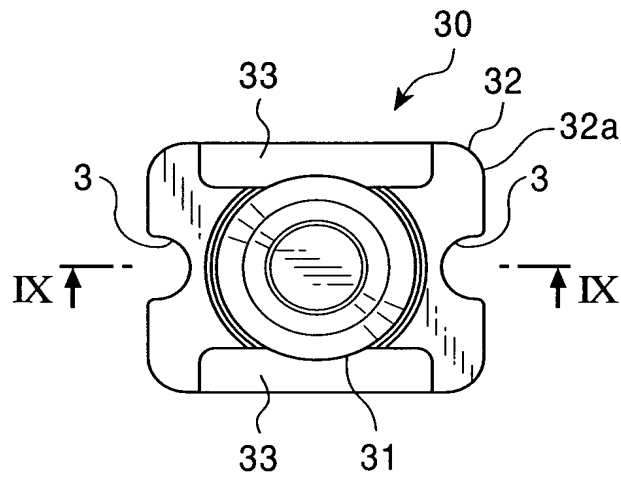


FIG. 8



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FIG. 9

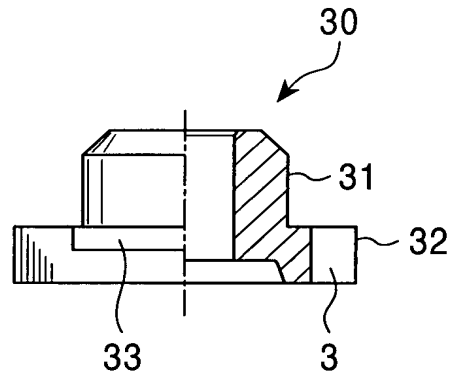
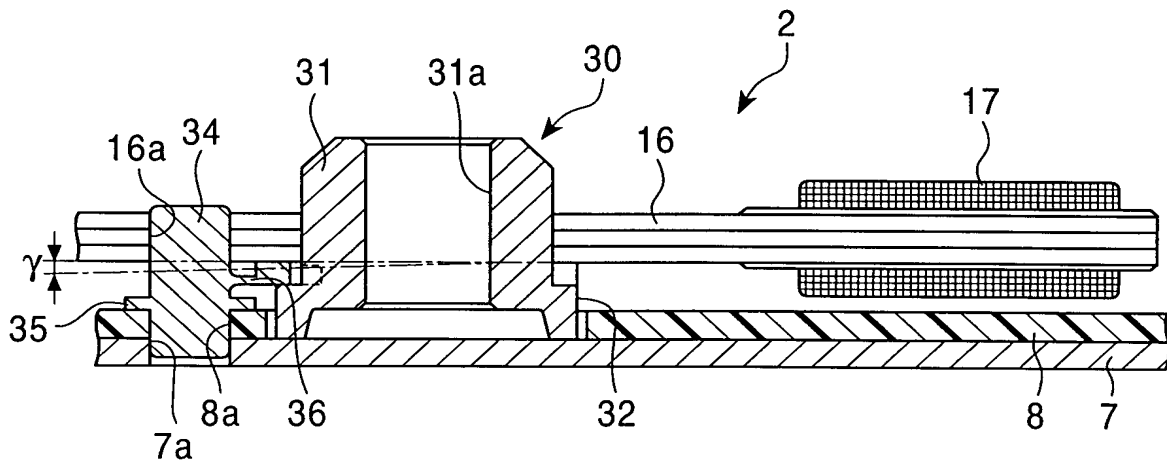
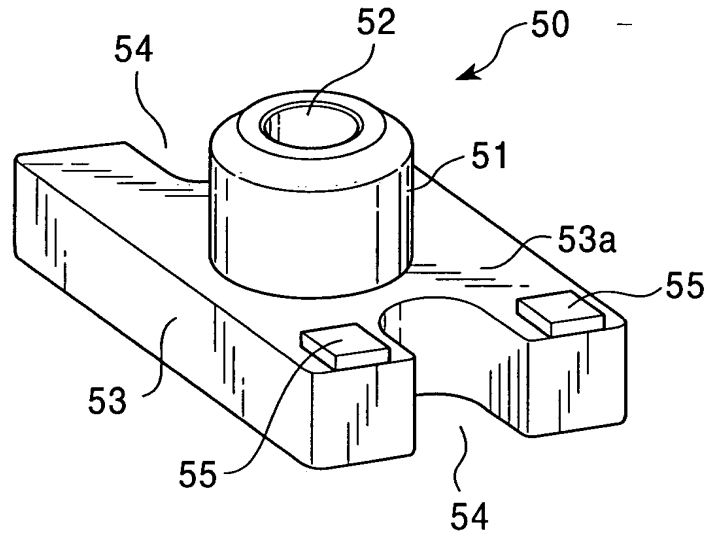


FIG. 10



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FIG. 11
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